IPC ASSOCIATION ELECTRONIC	Material Com © Copyright 2005. international and Pa	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				s Materials and	l Mfg Informati	on			
upplier	r Information													
Company name* Company uni				inique ID			Unique ID Authority				Response Date*			
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	Requester Item Number	Mfr Item	n Number	Mfr Item Name			Effective Date	Version	Manufacturing	Manufacturing Site		UOM	Unit Type	
		NCP133	7PG	PWM CONTROL	LER		2023-06-08		ID1		471.68	mg	Each	
	cturing Process Informa		Ci1 D	A11	-STD-020 MS	U. Datina	Deeds Doors	De des Tree	Mar Time	at Deals Town	N	f. D. fl C.	-1	
	3		Terminal Base Alloy J-STD-020 N CU Alloy NA			L Kating	Peak Process Body Temperature Max Time at O C 30			1.	seconds Number of Reflow Cycles Seconds 3			
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	information regarding materia	1		2										

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a								
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per t	he definition above except for defined Rol	IS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.19	mg	Supplier	Silicon (Si)	7440-21-3		2.19	mg
Die Attach	8.92	mg	Supplier	Silver (Ag)	7440-22-4		6.69	mg
			Supplier	Epoxy resins	129915-35-1		2.23	mg
Lead Frame	131.05	mg	Supplier	Silver (Ag)	7440-22-4		0.9173	mg
			Supplier	Zinc (Zn)	7440-66-6		0.2621	mg
			Supplier	Iron (Fe)	7439-89-6		3.4073	mg
			Supplier	Copper (Cu)	7440-50-8		126.4632	mg
Mold Compound-Black	317.53	mg		Epoxy Phenol Resin	proprietary data		33.3406	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		284.1893	mg
Plating	11.9	mg	Supplier	Tin (Sn)	7440-31-5		11.9	mg
Wire Bond	0.09	mg	Supplier	Palladium (Pd)	7440-05-3		0.0009	mg
			Supplier	Copper (Cu)	7440-50-8		0.0891	mg